Product End-of-Life Disassembly Instructions

Product Category: *Storage*
Marketing Name / Model [List multiple models if applicable.]
HPE Nimble Storage Expansion ES3-HXXXXX
HPE Nimble Storage Expansion AFS3

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	14
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	2 PSUs, 2 in Each PSU	4
External electrical cables and cords	2 Power Cables, 2 SAS cables	4
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

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Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Philips Screwdriver	P0,P1,P2
Standard Screwdriver	Medium
Diagonal Cutters	Small, Medium
Adjustable Wrench	4-6”
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove all the HDDs or SSDs from the front. Pop out the drives from the carriers and shred and dispose of properly per data protection protocols and contract(s) as applicable. Some customers may require certification of this step.
2. Remove Power Supplies from rear of Unit, disassemble by pulling off plastic tab on ejector, removing 20 screws and removing the PCBAs. Locate the 2 Electrolytic capacitors per the graphic below and cut or pry them off. Dispose of properly.
3. Remove the mounting ears from each side of the chassis in the front. Disassemble to remove the small PCBA in each ear and dispose of properly.
4. Slide the Controllers out the rear of the chassis and remove 3 PCBAs from each controller. Dispose of properly.
5. Remove the screws and the top cover to access the large midplane and the Power distribution board.
6. Remove Screws holding the power distribution board. Cut Cables or remove nuts holding cables to power distribution board. Dispose of properly
7. Remove the screws from the bottom of the chassis to release the Midplane. Dispose of properly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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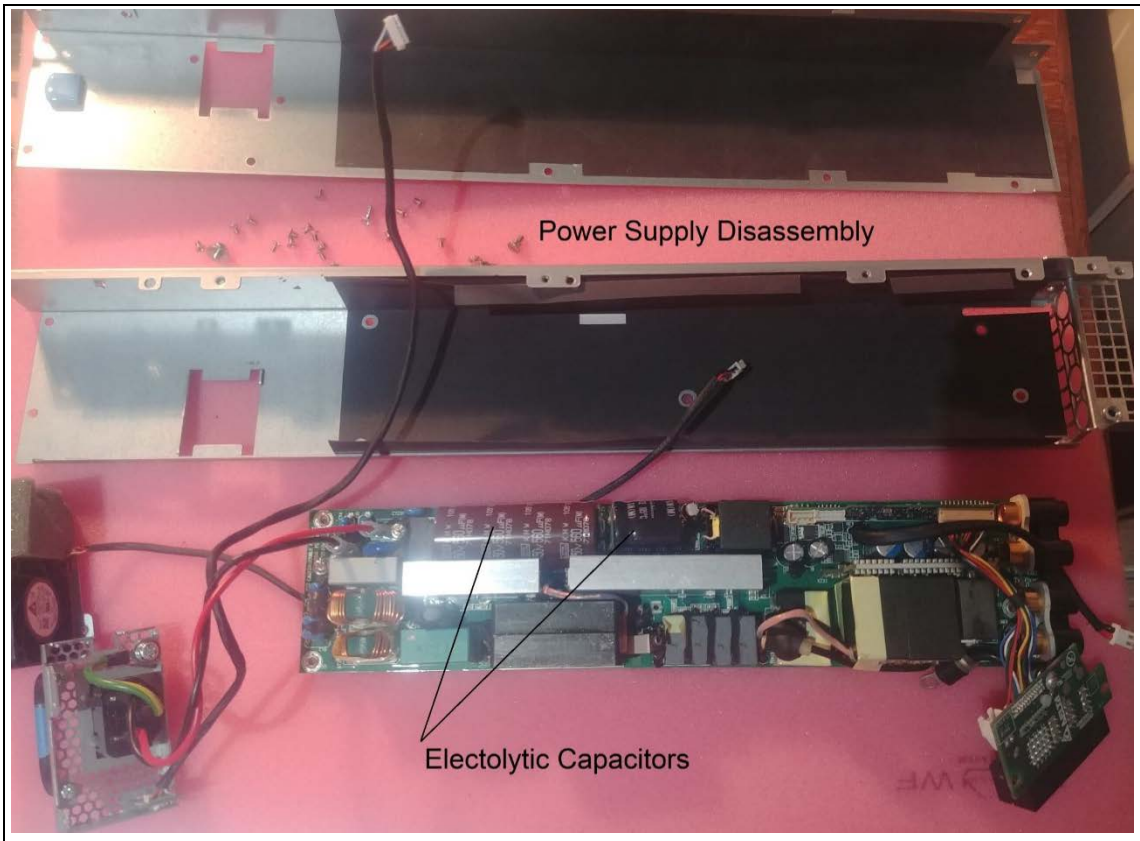
Power Supply



Mounting Ear:

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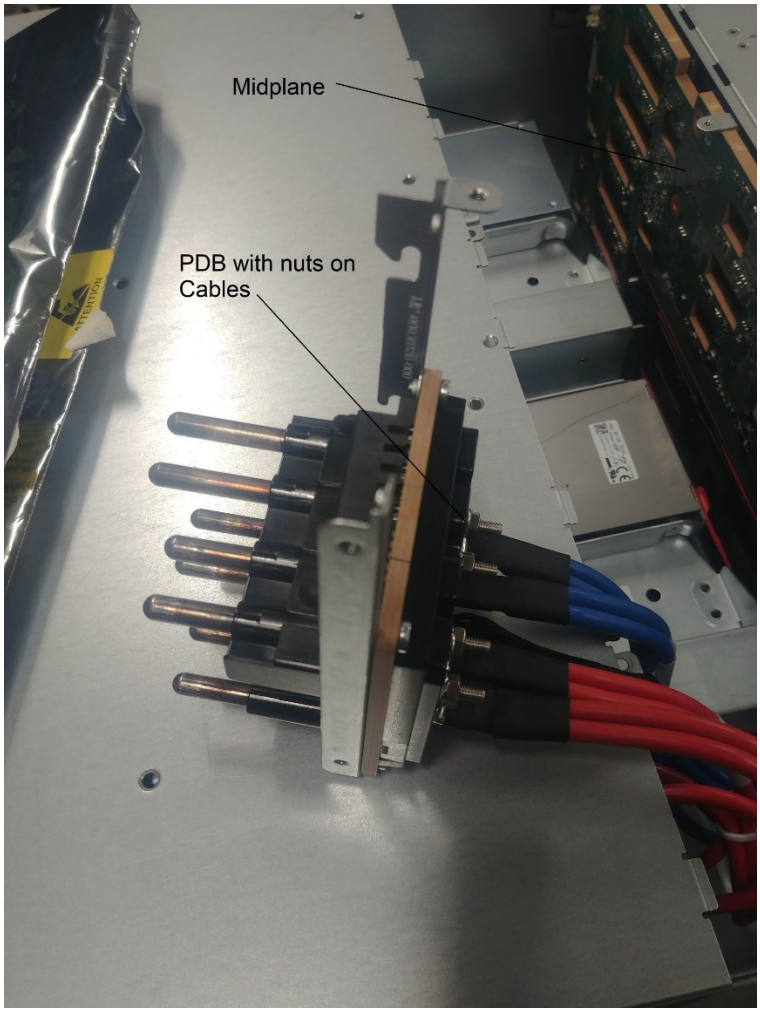
ES3 Controller

Power Distribution Board and Midplane



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